

Method for Improving Edge Peeling Defect

ABSTRACT OF THE INVENTION

5 A method for improving edge peeling defect is disclosed in
this invention. According to this invention, a wafer can be kept from
the edge peeling defect of the prior art by introducing a step for
removing the weakly adhesive films and the metal structures at the
wafer edge after forming a metal interconnect layer on the wafer. Thus,
10 this invention can raise the yield of semiconductor manufacturing, and
reduce the pollution chance of the chamber of the semiconductor
manufacture.